



From layout to chips

# Annual meeting - agenda

30 January 2020

08:45	Welcome coffee		
09:00 - 09:15	Introduction	J-Christophe Crébier	CMP
09:15 - 09:30	2019 Activity Results	Khouldoun Torki	CMP
09:30 - 09:50	Printed Electronics	Benoit Piro	Univ. Paris Diderot
09:50 - 10:05	0.35µm, 0.18µm Technologies	Lyubomir Kerachev	CMP
10:05 - 10:20	STMicroelectronics MPW services	Romain Verly	CMP
10:20 - 10:30	NANO2022 program	J-C Houdbert, Andreia Cathelin, François Martin	STMicroelectronics
10:30 - 11:00	Break discussion		
11:00 - 11:20	SMIC technology offer through CMP	Eliabetta Chierici, Massimo Bonanomi	SMIC
11:20 - 12:00	Panel on Photonics ICs:	Moderator: Romano Hoofman	IMEC
	VTT Si-photonic tech. on 3µm SOI platform	Matteo Cherchi	VTT
	CEA-LETI Si310-PHMP2M technology	Christophe Kopp	LETI
	AMF foundry offer through CMC-CMP partnership	Peter Stokes	CMC
	Teem Photonic's glass photonic platform, coupling solutions fiber-die	Arnaud Rigny	Teem Photonics
	Photonics MPW services @ CMP	François Berthollet	CMP
12:00 - 12:20	More than Moore technologies	Lyubomir Kerachev	CMP
12:20 - 13:00	Panel on new developments @ CMP:	Moderator: Khouldoun Torki	CMP
	Teaching module IP: from design to test	Sylvain Bourdel	RFIC Lab
	myCMP: one year of use	Christelle Rabache	CMP
	Add-On Services /IP	Jérémy Perret	CMP
	Visual inspection services	Nicolas Partenza	CMP
13:00 - 13:10	Closing remarks	Khouldoun Torki	CMP
13:10 - 14:30	Lunch discussion		